DECL. TION FOR PATENT APPLICATION (WITH POWER ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM INCLUDING SAME, the specification of which (check one):

☐ is attached hereto. ☐ was filed on August 20, 2001 as United ☐ was filed on as PCT intern		297. nd was amended under PCT A	Article 19 on	·
I hereby state that I have reviewed and und eferred to above.	derstand the contents of the above-ide	ntified specification, including	the claims, as amended	by any amendment
I acknowledge the duty to disclose to the Unatter claimed in this application, as "materia			e material to the patenta	bility of the subject
I hereby claim foreign priority benefits un certificate or § 365(a) of any PCT internations attached continuation page and have also ident PCT international application(s) designating a which priority is claimed.	der Title 35, United States Code, § 1 al application(s) designating at least o tified below and on any attached cont	19(a)-(d) or § 365(b) of any fonce country other than the Unimustion page any foreign appl	ted States of America listication for patent or investigation	ted below and on any entor's certificate or a
Prior foreign/PCT application(s):		'		
200104675-4 (mumber)	Singapore (country)	<u>06/08/2001</u> (day/month/year file	Priority ($\frac{X}{Yes}$	Claimed No
(number)	(comity)	(day/mondrycar in	au) les	
(number)	(country)	(day/month/year file	ed) Yes	No
pplication is not disclosed in any such prior a uty to disclose to the U.S. Patent and Traden tegulations § 1.56 which became available be (application serial no.)	nark Office all information known to	me to be material to patentabi plication and the national or P	lity as defined in Title 3	7, Code of Federal ate of this application
	·			
(application serial no.) I hereby claim the benefit under Title 35, I	(filing date) United States Code, § 119(e) of any U		pending, patented or abac cation(s) listed below:	inioner)
(provisional application no.)	(filing date)			
I hereby appoint the following Registered Paerewith:	ractitioners to prosecute this applicat	ion and to transact all busines	s in the Patent and Trade	emark Office connect
David V. Trask, Reg. No. 22,012 Joseph A. Walkowski, Reg. No. 28,765 Allen C. Turner, Reg. No. 33,041 Brick G. Power, Reg. No. 38,581 Krista Weber Powell, Reg. No. 47,867 Shawn G. Hansen, Reg. No. 42,627 Katherine A. Hamer, Reg. No. 47,628	William S. Britt, Reg. No. 20,96 James R. Duzan, Reg. No. 28,39 Edgar R. Cataxinos, Reg. No. 39 Paul C. Oestreich, Reg. No. 44,9 Jarett K. Abramson, Reg. No. 4 Bretton L. Crockett, Reg. No. 4 Michael L. Lynch, Reg. No. 30,8	H. Dickson I ,931 Kent S. Burr 83 Devin R. Jer 7,376 David L. Sto 4,632 Bradley B. J	Bond, Reg. No. 30,549 Burton, Reg. No. P-48, ningham, Reg. No. 30,45 asen, Reg. No. 44,805 att, Reg. No. 43,937 ensen, Reg. No. 46,801 trantley II, Reg. No. 38,	53
TRAS P.O.	ey B. Jensen, telephone no. (801) 53 KBRITT, PC BOX 2550 Lake City, Utah 84110	2-1922.		
I hereby declare that all statements made he d further that these statements were made with, under Section 1001 of Title 18 of the Unitsued thereon.	th the knowledge that willful false sta	tements and the like so made	are punishable by fine of	r imprisonment, or
ull name of first joint inventor: Setho Sing Fewentor's signature	* 9t	Date	129/01	
esidence: Singapore itizenship: Republic of Singapore ost Office Address: Block 91, Bedok North S	treet 4, #11-1523, Singapore 460091	. (7	

DECLARATION FOR PATENT APPLICATIO (continuation page)

Date

Invention title: QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM **INCLUDING SAME**

Inventor name(s) appearing on first declaration page: Setho Sing Fee

Additional original, first and joint inventor(s):

Full name of second joint inventor: Lim Thiam Chye

Inventor's signature

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